

Tatsuta EMI Shielding Solutions

May 30, 2019

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TATSUTA ELECTRIC WIRE & CABLE Co., Ltd

Conductive Materials Division

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1 Company Profile

2 Products Lineup

EMI Shielding Conductive Paste

EMI Shielding Film

3 Equipment

EMI Shielding Process Equipment

EMI SE Measurement Equipment

4 Dry Process Printed Electronics Solutions

5 5G/6G EMI Shielding & Thermal Management Solutions

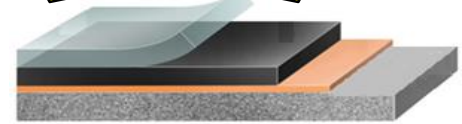
6 Roadmap

Company Profile

TATSUTA

JXTG Holdings

#1 Market Share
EMI Shielding
Film



Functional Materials

FPC EMI Shielding Film
Bonding Film
Free GND Film

Conductive Paste

PKG EMI Shielding Paste
LCP Via Filling Paste
Antenna Printing Paste

Fine Wire

Au, Ag, Cu Wire

TATSUTA
ELECTRONIC MATERIALS

Electric Wire&Cable

Electronic Materials

JX JX Nippon Mining & Metals

RA Cu Foil
6N Cu Ingot
Cu Target
Cu Powder

LCP FCCL

JXTG Nippon Oil & Energy

LCP Nugget

ENEOS

LCP FCCL



Company Profile

Company Profile	
Established	September 28, 1945
Capital	6.676 billion yen (as of March 2018)
Sales	Consolidated: 55.1 billion yen (Fiscal year end, March 2018) Non-consolidated: 47.4 billion yen
Employees	Consolidated: 852 (Fiscal year end, March 2018) Non-consolidated: 521
Main products	Electric wire/cable (power, optical fiber, communications), Electronic components and materials, Device system products, Optical products



Suzhou Support Center



USA



Shanghai



HQ



Sendai Works



Malaysia



Kyoto Works



Technical Center Kizugawa Works

Products Lineup in System Electronic Division

Conductive Paste

- EMI Shielding
(Conformal & Compartment Shielding)
- Via filling
(Electric conductive & Thermal Conductive)
- Circuitry / Electrode (Solderable)
- SMT(Low Temp. Curing)



Functional Film

- EMI Shielding film
(Thermosetting, Thermoplastic, PSA type)
- Free Grounding film
- Bonding film
(Conductive , Non-Conductive type)
- Masking film for reflow process



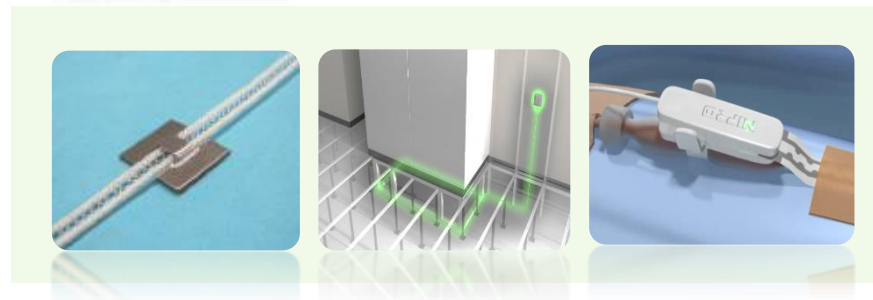
Bonding Wire

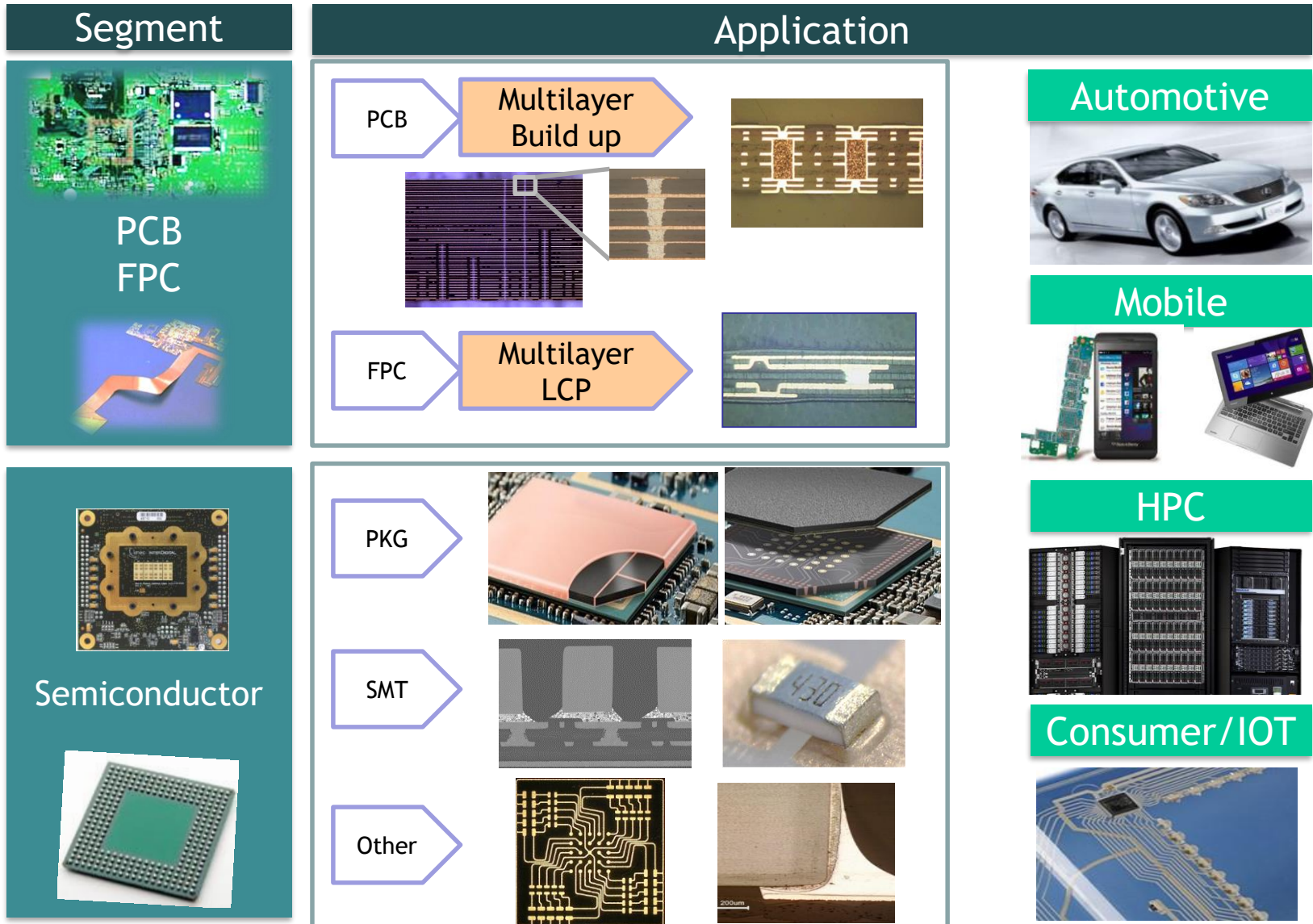
- Gold bonding wire
- Copper bonding wire
- Silver bonding wire



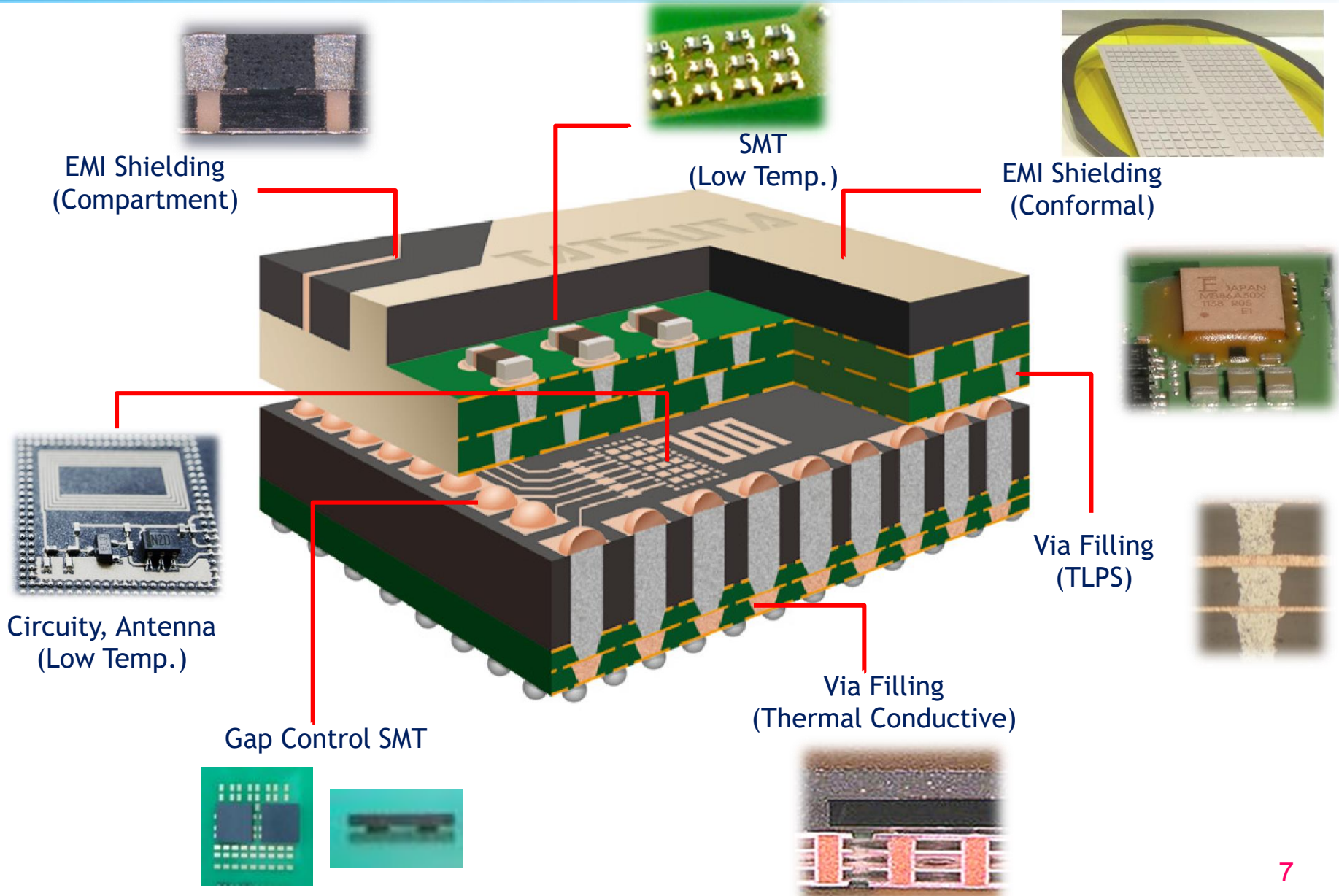
Sensor

- Water Leakage Sensor
- Medical Sensor

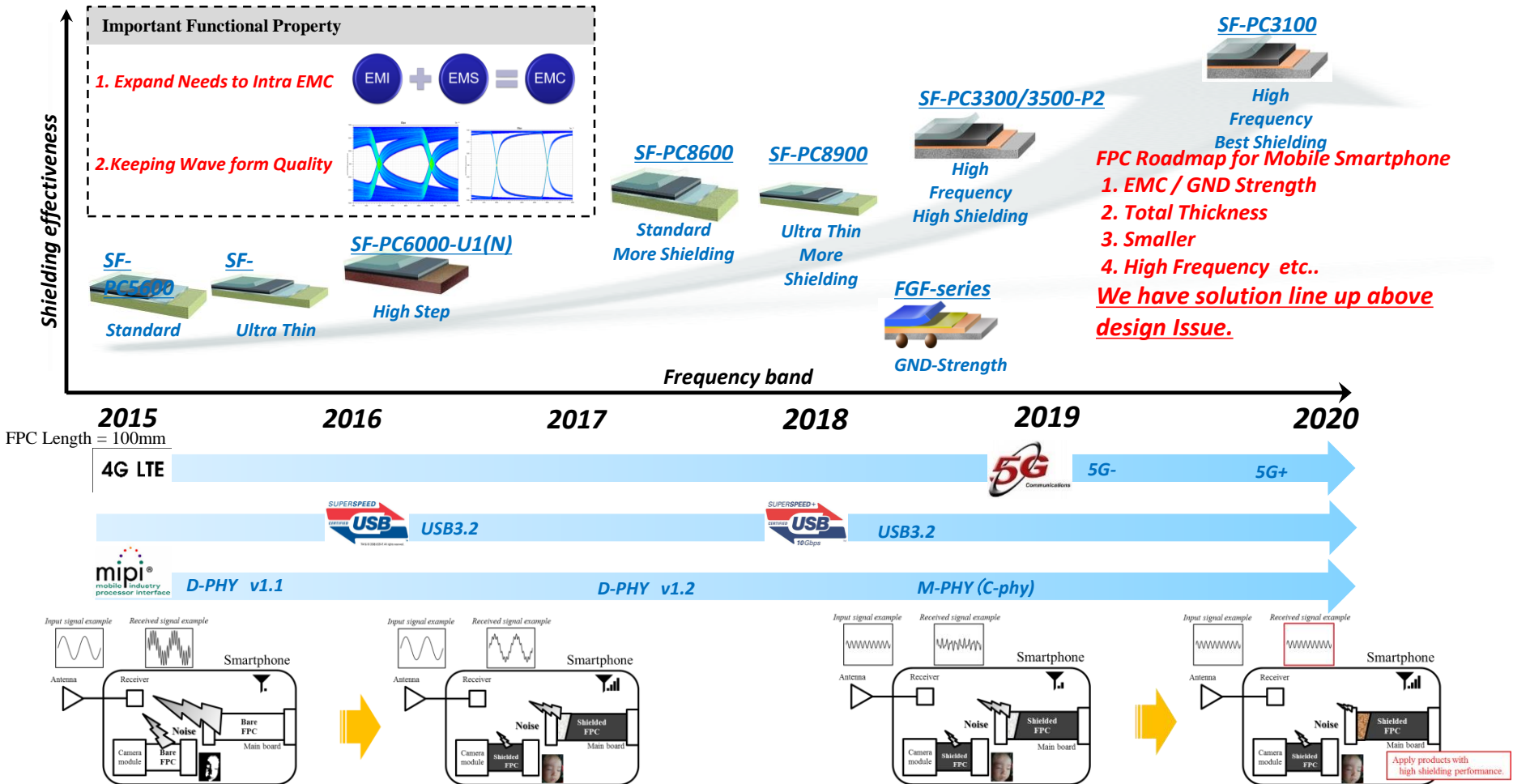




Paste Lineup for PCB/FPC and Semiconductor



EMI Shielding Film Road Map with Signal Environment



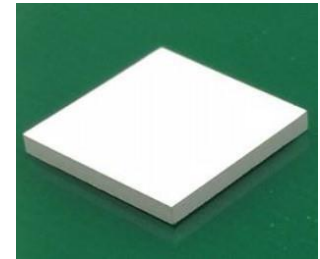
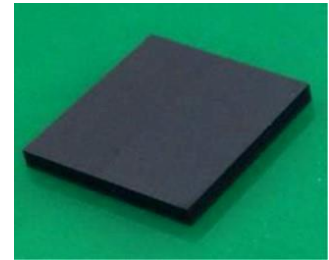
Conformal Spray Coating

Nordson Asymtek

Ultrasonic Systems

Protec

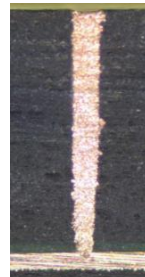
Spray



Compartment Trench Filling

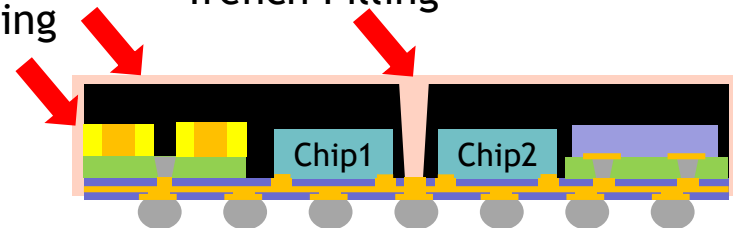
Vacuum Printing
Toray ENG

Dispensing & Jetting
Nordson Asymtek



Conformal Coating

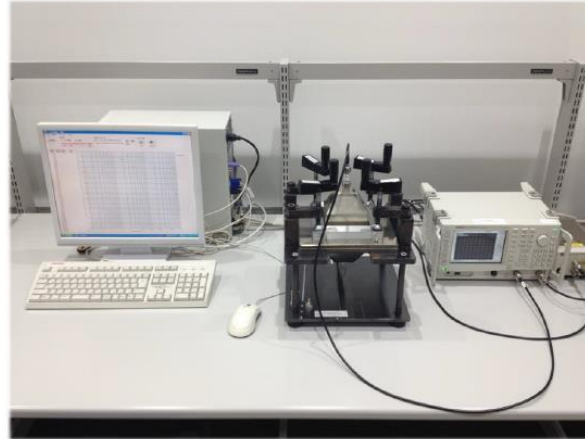
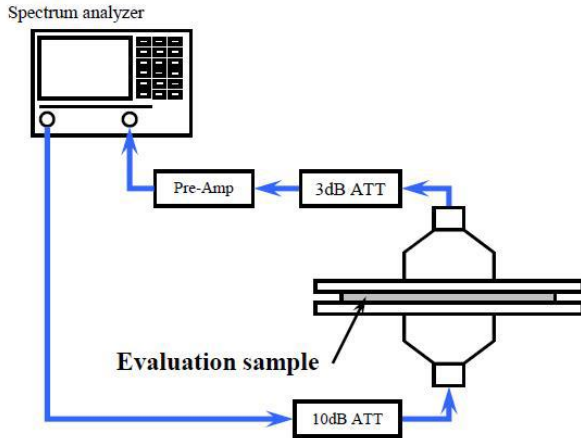
Compartment Trench Filling



Radio Isolation Room



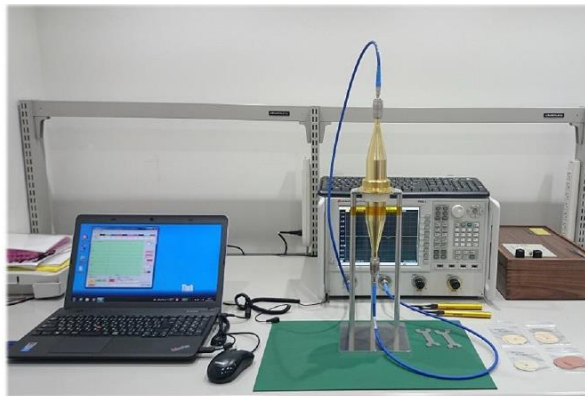
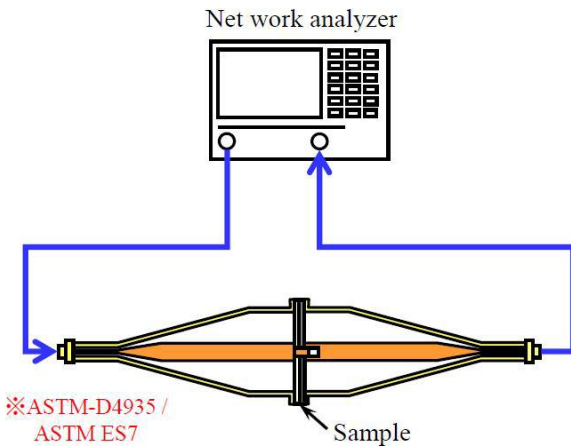
KEC Method (Max 1GHz)



Coaxial Tube Method (Max 10GHz)



Next
28GHz SE
Measurement
Equipment

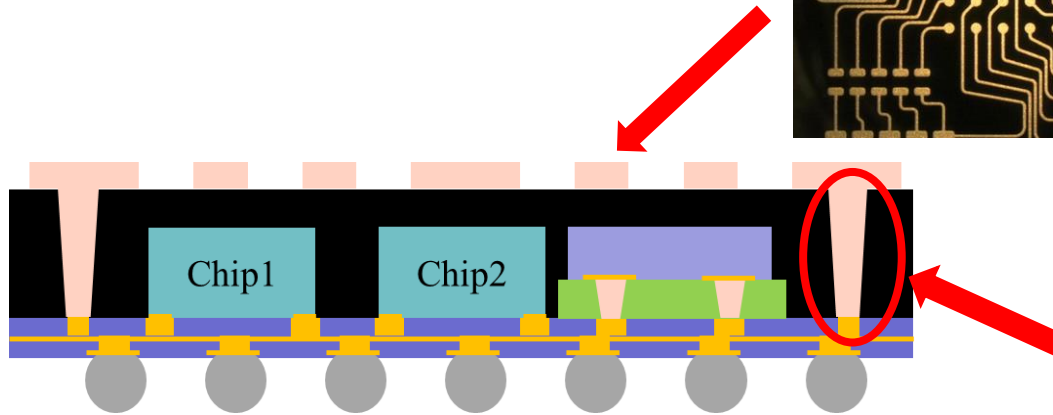
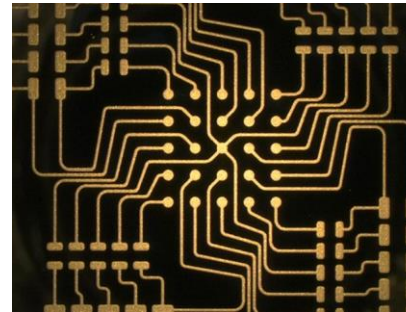


Dry Process Printed Electronics Solutions

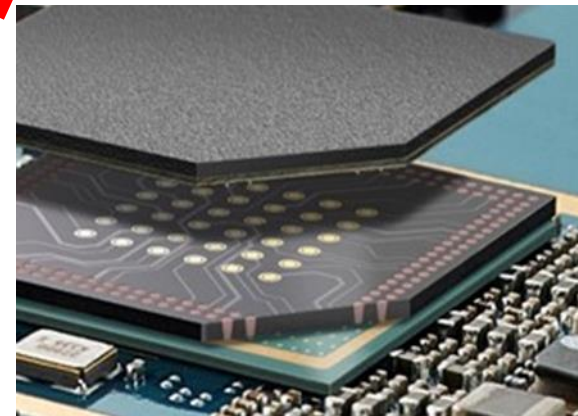
TATSUTA

Antenna

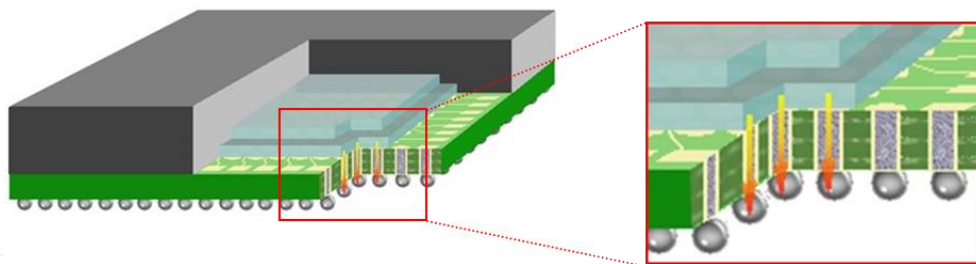
RDL



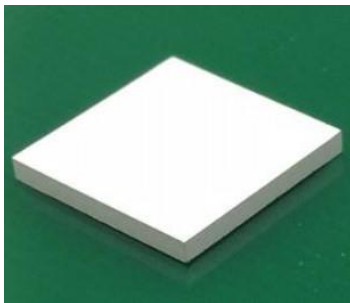
FMV



Thermal Via



Sputter/Spray



IC PKG
Small Size

Spray & Jetting



SiP & Entire Board
Large Size

Thermal Release + EMI Shielding

Process

Stress Free Spray Coating for Wide Area
Paste Filling in Narrow Trench and Micro FMV
Low Temperature Curing

Material

Thin & High SE Hybrid Metal Formulation
High Peeling Strength Resin Formulation

Roadmap

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